

**Amendments to the Claims:**

Following is a complete listing of the claims pending in the application as amended:

**CLAIMS**

1. (Original) A method for manufacturing a door mold, comprising:
  - a masking/sanding process (S100) of making a non-etching area except an etching area of the mold and then finishing the etching area with sand to transfer a pattern on the etching area;
  - a pattern forming process (S200) which comprises a pattern transfer step of transferring a film printed with the pattern onto the etching area of the mold, a correction step of correcting connection and non-matched portions of the pattern, a precise masking step of precisely masking the non-etching area of the mold for its protection, an etching step of performing an etching operation with chemicals selected in accordance with a mold material and the pattern, and a cleaning step of cleaning the etching area of the mold with an alkaline solution and/or a sanding step of finishing the etching area with sand;
  - a mesh forming process (S300) which comprises a mesh transfer step of transferring a predetermined mesh onto the etching area using a spraying method after the pattern forming process has been completed, an etching step of performing an etching operation with chemicals selected in accordance with the mold material and the mesh, and a sanding step of finishing the etching area with sand;
  - a polishing process (S400) of performing polishing treatment by spraying glass beads on the etching area such that the degree of polish of the etching area can be uniformly maintained; and
  - a mask removal/inspection process (S500) of removing a mask material from the non-etching area of the mold and then performing anticorrosive treatment on the surface of the mold after the polishing process has been completed.
2. (Original) The method as claimed in claim 1, wherein the pattern forming process (S200) is repeatedly performed at least twice.
3. (Original) The method as claimed in claim 1, wherein the mesh forming process (S300) is repeatedly performed at least twice.

4. (Original) The method as claimed in claim 1, wherein etching depths in the mold during the pattern and mesh forming processes are different from one another.
5. (Original) The method as claimed in claim 3, wherein etching depths in the mold during the mesh forming process (S300) are within a range of 0.02 to 0.05mm.
6. (Original) The method as claimed in claim 1, wherein 70 to 99 vol% of the glass beads are used in the polishing process (S400).
7. (Canceled)